## PATENT ASSIGNMENT

# Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
Anthony Leanza	03/26/2010

### **RECEIVING PARTY DATA**

Name:	Honda Motor Co., Ltd. (a corporation of Japan)	
Street Address:	No. 1-1, Minami-Aoyama 2-chome, Minato-ku	
City:	Toyko	
State/Country:	JAPAN	
Postal Code:	107-8556	

## PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12748599

## CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	32776_005_H1094824U\$02
NAME OF SUBMITTER:	Brian D. Kennev

Total Attachments: 1

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PATENT REEL: 024152 FRAME: 0001

#### **ASSIGNMENT**

I, Anthony Leanza, of Powell, Ohio 43065 US, has (have) made an invention which now is described and claimed in an application for patent entitled **OVERMOLDED JOINT FOR BEAM ASSEMBLY**, which application

is being executed and filed concurrently herewith; and

 $\boxtimes$  which application claims priority to provisional application filed on <u>December 6, 2009</u> (United States patent application number serial no. <u>61/267,063</u>).

NOW THEREFORE, pursuant to the obligations imposed by or arising under one or more of my employment agreement(s), advisor agreement(s), state or national statutes, common law, and administrative regulation, I hereby do make the following assignments -

To **HONDA MOTOR CO., LTD.**, (a corporation of Japan), a corporation created and duly organized in Japan and having a place of business at No. 1-1, Minami-Aoyama 2-chome, Minato-ku, Tokyo 107-8556, JAPAN, and its successors and assigns, I hereby

- assign, transfer, and set over the full and exclusive right to the above-described invention and to the above-described applications for letters patent of the United States as well as any substitute, continuation, continuation-in-part, or divisional application filed thereon, to any application for letters patent of the United States that claims priority from the above-described applications, and to any letters patent of the United States that issues from such applications as well as any reissue application or request for reexamination filed on such letters patent;
- covenant and agree for myself and my legal representative(s) to
  - a) assist said assignee and/or its designee(s), to the extent requested, in the prosecution of said applications for patent, in any interference declared on said applications for patent or patent issuing therefrom, or in litigation which arises out of or is based on said applications for patent or patent issuing therefrom, and
  - b) execute all papers related to said applications for patent which said assignee or its designee(s) request to be signed,

provided that expenses relating thereto shall be borne by said assignee; and

• authorize and request the Commissioner of Patents and Trademarks to issue any letters patent of the United States relating to the above-described invention in the name of said assignee.

IN WITNESS WHEREOF, I have executed this document on the date next to my name.

Anthony Leanza

 $\frac{3/26/10}{\text{Date}}$ 

REEL: 024152 FRAME: 0002

PATENT Doc 3498570 Ver 1